Preface

Dear Distinguished Delegates and Guests,

3rd International Conference on Intelligent Structure and Vibration Control 2013 (ISVC2013) was held in Chongqing, China, from March 22-24, 2013, serving as a platform for expertise exchange. ISVC 2013 had drawn the attention of researchers from various disciplines: Advanced Intelligent Structure, Bio-inspired Smart Materials and Structures, Materials for energy storage, Active Materials, Mechanics and Behavior, Vibration and Control, Modeling, Simulation, Control and Applications, Fuzzy System and Fuzzy Control, Management Information Systems, etc.

Persons who attended the conference were engineers, scientists, managers of various companies and professors of the universities abroad and home. We have had record number of submission 452 this year. Only original and unpublished paper would be considered, and 107 papers have been accepted for presentation at the conference and will be published by TTP, in Applied Mechanics and Materials (AMM) Journal (ISSN: 1660-9336), which is online available in full text via the platform www.scientific.net. AMM should be indexed by EI according the previous TTP index results.

We express our special gratitude to all the members of the General Committee Chairs, Program Committee Chairs, Technical Program Committee and Steering Committee who worked so hard to prepare the conference and who supported the conference so professionally.

Our deep thanks also go to the sponsors: Shanghai Jiao Tong University, Nanyang Normal University, Hebei Polytechnic University, Henan Institute of Science and Technology, Chongqing University of Arts and Sciences, Hunan Institute of Engineering, their kind support in making ISVC 2013 possible.

Finally, we would like to thanks all the authors, speakers and participants of this conference for taking part in and contributing to the International Conference on Intelligent Structure and Vibration Control 2013.

We hope you have a unique, rewarding and enjoyable week at ISVC 2013 in Chongqing.

With our warmest regards,

ISVC2013 Organizing Committees
March 22-24, 2013
Chongqing, China

ISVC 2013

Committees

Conference Chairs

J.X. Chen, Gradiant ETSI Telecomunication, Spain

B.Gao, Centrum Wiskunde & Informatica, the Nethelands

Y.M.Cheng, and Yanshan University, China

Program Committee Chairs

B.J. Zhang, Henan Institute of Science and Technology, China

A.M.Yang, Hebei Polytechnic University, China

K.X. Wei, Hunan Institute of Engineering, China

Organizing Chair

M.N.Gui, Texas State University, USA

L. Wang, Hebei Polytechnic University, China

Contact Co-Chairs

G.C. Zhou, Hebei Polytechnic University, China

J.G.Qu, Hebei Polytechnic University, China

Publication Chair

C. Li, Chongqing Normal University, China

X.L.Qu, Hunan Institute of Engineering, China

Technical Program Committee

J.N. Jue, University of Texas at Dallas, USA

C.X. Zhang, Juniper Networks, USA

J.X. Chen, University of Vigo, Spain

L. Zhou, ENSTA-ParisTech, France

R.C. Tang, Ocean University of China, China

H.R. Yoshino, NTT, Japan

A.M. Yang, Hebei United University, China

M.N. Devetsikiotis, North Carolina State University, USA

C.J. Wang, Northwestern University, USA

M. Chen, NEC Laboratories America, USA

Z.X. Duan, Florida State University, USA

N.X. Ghani, University of New Mexico, USA

W.J. Kabacinski, Poznan University of Technology, Poland

S.R. Subramaniam, George Washington University, USA

M.Y. Gao, National Institute of AIST, Japan

S.H. Yan, Hebei United University, China

Y.J. Guo, Huazhong Normal University, China

H.B. Yin, Peking University, China

B.A. Mark, George Mason University, USA

A.H. Khalil, City University of New York, USA

M.K. Pickavet, Ghent University, Belgium

R. Zhu, South-Central University for Nationalities, China

M.J. Gagnaire, ENST, France

L.J. Xu, University of Nebraska-Lincoln, USA

S.M. Khan, North Dakota State University, USA

D.B. Shupke, Nokia Seimens, Germany

J.G. Qu, Hebei United University, China

C.H. Assi, Concordia University, Canada

Y.Z. Zhang, Simula Research Laboratory and University of Oslo, Norway

G.F. Gui, CMC Corporation, China

H.Y. Bao, NTT Co., Ltd., Japan

X.W. Hu, Wuhan University of Technology, China

Y.W. Zou, Apple China Co., Ltd., China

L.W. Li, Northwestern University, USA

S.Z. Zheng, University of Texas at Dallas, USA

X.W. Hu, Wuhan University of Technology, China

S.B.Zhong,Chongqing Normal University,China

X.Y. Bai, University of Western Ontario, Canada

A.S. Shami, University of Western Ontario, Canada

M.X. Brunner, NEC Europe Labs, Germany

A.R. Forte, Columbia University, USA

D.X. Gong, Hebei Polytechnic University, China

I.R. Guardini, Telecom Italia Lab, Italy

E.R. Hossain, University of Manitoba, Canada

D.W. Niyato, Nanyang Technological University, Singapore

L.X. Le, Massachusetts Institute of Technology, USA

M.Z. Liao, Cisco China R&D Center, China

L.C. Feng, Hebei Polytechnic University, China

Y. Lin, Norwegian University of Science and Technology, Norwegian

Y.J. Li, Shanghai Jiao Tong University, China

J.W. He, Swansea University, UK

P.B. Hui, University of Cambridge, UK

L.-J. Chen, Academia Sinica, Taiwan

Y.L. Jin, Shanghai University, China

B. Choi, University of Missouri at Kansas City, USA

M.Y. Shi, University of Waterloo, Canada

ISVC 2013 Reviewers

T.R. Melia, Cisco Systems, Switzerland

W.M. Eddy, NASA/Verizon, USA

H.R. Haddadi, University College London, UK

J.H. Ott, Helsinki University of Technology, Finland

S.-Y. Hua, National Central University, Taiwan

K.J. Li, University of Georgia, USA

G.H.Gao，Henan Institute of Science and Technology ,China

M.J. Stiemerling, NEC Europe Labs, Germany

F. Kuo, University of Goettingen, Germany

J.G. Qu, Hebei United University, China

J.X. Chen, University of Vigo, Spain

R.C. Tang, Ocean University of China, China

L.X. Shi, IBM Research Lab, China

R. Zhu, South-Central University for Nationalities, China

G.X. Danilewicz, Poznan University of Technology, Poland

Y.Z. Xu, Polytechnic University, USA

K.W. Xu, Arizona State University, USA

H.J. Wang, College of William and Marry, USA

C.X. Wu, University of Toronto, Canada

S.H. Yan, Hebei United University, China

W.M. Zhang, North Dakota State University, USA

D.L. Liu, ShenYang Ligong University, China

Y.X. Tang, Illinois State University, USA

L. Zhou, ENSTA-ParisTech, France

A.M. Yang, Hebei United University, China

W.X. Wei, NEC Labs America, USA

Y.L. Zhao, Northwestern University, USA

G.F. Gui, CMC Corporation, China

A.D. Baiocchi, University of Roma, Italy

L.C. Feng, Hebei Polytechnic University, China

M.Z. Liao, Cisco China R&D Center, China

O.X. Altintas, Toyota InfoTechnology Center, Japan

S.J. Giordano, University of Pisa, Italy

Y. Lin, Norwegian University of Science and Technology, Norwegian

Y.W. Zou, Apple China Co., Ltd., China

X.G. Zhang, Nanyang Normal University, China

Z.G. Wei, Beijing Forestry University, China

Y.J. Li, Shanghai Jiao Tong University, China

H.B. Nguyen, The Aerospace Corporation, USA

D.U. Sarkar, University of Miami, USA

H.Y. Bao, NTT Co., Ltd., Japan

C.A. Wei, Hainan Medical University, China

X.W. Hu, Wuhan University of Technology, China

S.B. Zhong, Chongqing Normal University, China

Z.Q. Liu, AT&T, USA

I.R. Guardini, Telecom Italia Lab, Italy

Y.L. Jin, Shanghai University, China

E.R. Hossain, University of Manitoba, Canada

D.X. Gong, Hebei Polytechnic University, China

D.W. Niyato, Nanyang Technological University, Singapore

L.X. Le, Massachusetts Institute of Technology, USA

H.Chen, Hu'nan University, China

L.L. Wang, Beijing University of Posts and Telecommunications, China